### Integrated High Speed VCSELs for Bi-Directional Optical Interconnects

#### Volodymyr Lysak, Ki Soo Chang, ong Tak Lee

(GIST, 1, Oryong-dong, Buk-gu, Gwangju 500-712, Korea, T el: +82-62-970-3129, Fax: +82-62-970-3128, Email: lysak@gist.ac.kr)

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#### Outline

- Introduction
- Model description
- Structure optimization of VCSEL
- Conclusions



## **Computers: past, present and future**



Cray X1 2000s

PC 2020s



http://www.cray.com

# Computer I/O architecture history and I/O roadmap



Beyond 10 GHz, copper interconnects, become bandwidth limited due to frequency-dependent losses such as the skin effect in the conductors and the dielectric loss from the substrate material.

#### We need the optoelectronic devices with

- good performance (high-modulation bandwidth, low power consumption, high efficiency)
- manufacturing advantages (amenable to high-volume production, wafer-level testing, and ease of integration).
  - E. Mohammed et.al, Intel Technology Journal, V.8 N.2, 2004, pp. 115-127

### VCSELs over Edge Emitter lasers



VCSELs Vs EEs (Arrays) Edge Emitting Laser Arrays/Discrete Cleaved facets - yield? Facet coatings for lth- stress? No wafer testing - cost? Elliptical O/P beam - cost? t package before test: acturing Expensive VCSEL Arrays/Discretes: Probing like silicon - low cost Die sawn like silicon - high yield Low Threshold - low power drain Circular O/P beam - small spot size Flip-chip - Low cost packaging obe & Wafer Map for KGD before er Die Costs and Lower System

VCSEL (Vertical Cavity Surface Emitting La

- VCSELs are characterized by:
- I ow threshold Current.
- High power conversion efficiency.
- Less heating.
- Convenient operating wavelength.
- High speed of operation > 10 GHz.
- Surface normal light output.
- Circularly shaped, low NA output beams.
- Small size compared to other kinds of laser diodes
- Very good potential for 2D arrays.
- Low cost wafer scale fabrication.
- Important space applications:
- High speed fiber optic networks.
- Free space optical communication.
- Optical interconnects.
- Optical storage systems.



### P-contact

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- + Bypass the current flow through mirrors ⇒ lowers the series resistance
- + Use of undoped DBR mirror
  - $\Rightarrow$  reduce free carrier absorption
  - $\Rightarrow$  better reflectivity
- + Co-planar contact
  - $\Rightarrow$  suitable for flip-chip bonding
- Current crowding effect

## Intracavity contacted VCSEL array



## Interactions between physical processes in LD



#### **PICS3D Crosslight program**



#### **Total current magnitude for different pumping currents**



#### **Thermal phenomena**





Steady-state Optical wave absorption Recombination Thomson Peltier heat Electrical field on loss semiconductors heat heat





#### Heat sources in ICOC VCSEL





#### **Graded layer thickness I**

I-L and I-V characteristics and energy band diagram in the center of structure for different values of graded layer thickness (GLT)





V. V. Lysak, et. al, Appl. Phys. Lett. 87 (2005), 231118 1-3



#### **Graded layer thickness II**

Radial distribution of electron concentration

f3dB bandwidth



 $\mathsf{GLT} \uparrow \rightarrow \mathsf{current} \ \mathsf{crowding} \ \mathsf{effect} \uparrow$ 

GLT↓→Rtot↑ → f3dB↓ GLT ↑→Veff↑ + nonuniform current distribution → f3dB ↓



#### **Contact layer thickness I**

Contact layer is a part of DBR mirror  $\rightarrow d=(2k+1)\lambda/4n$ 

a) V-I and b) L-I characteristics for different values of n - and p - contact layer thickness of  $\lambda/4n$  (solid lines),  $3\lambda/4n$  (dashed lines),  $5\lambda/4n$  (dash-dotted lines) and  $7\lambda/4n$  (dotted lines)





#### **Contact layer thickness II**



Radial distribution of the lattice temperature in active layer

Radial distribution of the electron concentration



 $\mathsf{CLT}^{\uparrow} \to \mathsf{R}_{\mathsf{layer}}^{\downarrow} \to \mathsf{R}_{\mathsf{tot}}^{\downarrow} \to \mathsf{T}_{\mathsf{active}}^{\downarrow} \to \mathsf{Gain}^{\uparrow}$ 





Decreasing the CLT increases the differential resistance (see V-I characteristics). On the other hand, increasing the CLT changes the parameters as follows: increases the effective volume of resonator and decreases the gain enhancement factor due to increasing the penetration depths of DBR mirrors; reduces differential gain from the current crowding effect



#### **Capacitance management**





 $\mathbf{C}_{ox}$  Counter-flowing paths for electrons and holes  $\longrightarrow$  asymmetrical contacts and suppress the conductivity

#### **Experimental part**

#### **L-I-V characteristics**



small signal modulation





- Oxide aperture dia. : 5 µm
- Threshold current : 0.7±0.05 mA
- Threshold voltage : 1.7 V
- Slope efficiency : 0.36±0.01 W/A @ I=2mA
- Differential quantum efficiency:

28.4±0.7 %@ I=2mA

> Differential resistance : 150  $\Omega$  @ I=6mA







#### Conclusion



- we have analyzed the thermal, electrical, optical, and modulation properties of the 980 nm InGaAs ICOC VCSELs with different geometrical values
- devices with the optimal GLT of 40-60 Å have the highest output power and the widest modulation bandwidth due to compromise between the low resistance and more uniform radial carrier distribution in the active layer
- devices with the optimal CLT of 5λ/4n have the widest modulation bandwidth and the modulation conversion efficiency factor is approximately 5.92 GHz/(mA)<sup>0.5</sup> due to compromise between the effective volume of resonator, current crowding suppression and total resistance
- The VCSEL with 5 mm diameter oxide aperture has a threshold current of 0.7 mA, a threshold voltage of 1.7V and a maximum output power of 7mW.
  0.36W/A slope efficiency at 6mA and 29% differential quantum efficiency were achieved at room temperature. A maximum 3dB modulation frequency at a bias current of 10mA reached 10 GHz.

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